

# Highlights

- Suitable for metals as well as hard materials, ceramics and workpieces with sharp edges
- All outside diameters possible
- Outstanding lifetime and economy compared to the competition
- New generation with50 % more grinding layer
- Cleaner than lapping with grinding suspensions
- High flatness, surface quality and precise edges

Diamond grinding pad

# SQUADRO-M2/SQUADRO-H2

SQUADRO-M2 and SQUADRO-H2 are the second generation of the proven and highly efficient SQUADRO-M and SQUADRO-H diamond grinding pads. The highly innovative diamond grinding pads are optimized for fine grinding of metals, hard materials, ceramics and workpieces with sharp edges. They combine all the advantages of SQUADRO-M and SQUADRO-H respectively.

The new, improved manufacturing process allows significantly greater flexibility in the production of different diameters and 50 % more grinding thickness. Accordingly, they offer a significantly better lifetime compared to the already outstanding lifetime of the previous generation. In terms of application, SQUADRO-M2 and SQUADRO-H2 offer high and uniform stock removal over the entire lifetime as well as impressive surface qualities and edge sharpening. Thanks to their long lifetime and easy handling, SQUADRO-M2 and SQUADRO-H2 are an economical and efficient alternative to other grinding pads or conventional lapping methods.

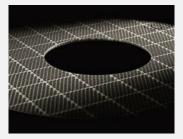
## Typical applications

SQUADRO-M2: Fine grinding of metals

SQUADRO-H2: Fine grinding of hard materials, ceramics and sharp-edged workpieces

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# **PUREON**



Diamond grinding pad SQUADRO.



Close-up on grinding pad SQUADRO.



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### **Product specifications**

Abrasive layer thickness ..... 0,6 mm

SQUADRO-H2: Resin, hard

Carrier material ...... Polycarbonate

### Order information

Order code SQUADRO-M2 3-OD700-ID200mm-PU1-PSA-D1

• Diamond size ...... 3 μm, 6 μm, 15 μm, 30 μm, 60 μm (125 μm only SQUADRO-H2)

Outer diameter 200 mm – 1'200 mm one-piece
For bigger diameters multi-piece

Custom sizes are available upon request

Inner diameter ...... Optional (freely selectable)

• Packing unit ...... 1 piece/box

Backing / mounting ......PSA (self-adhesive)

SGM (metal plate) MAG (magnetic foil)

Optional

### Application recommendations

Dressing Prior to the first use, the SQUADRO-M2 and SQUADRO-H2 pads have to be dressed and planarized with a dressing tool (e.g. Al<sub>2</sub>O<sub>3</sub> with grit 280 mesh (grit size 60 µm, 125 µm) or 400 mesh

(grit size  $3 \, \mu m$ ,  $6 \, \mu m$ ,  $15 \, \mu m$ ,  $30 \, \mu m$ )).

Cleaning ...... To ensure cutting efficiency of the bonding, the

grinding pad has to be cleaned from abrasive debris regularly. Best suited for this are brass brushes for manual or machine use. Machine brushes can be

ordered from Pureon as accessories.

water-soluble cooling and lubricating fluid that ensures high and consistent material removal. DI-water is only partly suited. No dry running. Organic solvent and oil based lubricants may harm the pad and are therefore not recommended.

# Grinding parameters

Grinding pressure Recommended: 2 – 10 N/cm2, max. 15 N/cm2

Circumferential speed ........... Recommended: 5 m/s, max. 10 m/s

### Contact

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